

INT-03-002



May 11, 2004

To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:	Serial No. 10/782,364 02/19/04
	Thomas Aisenbrey
	TRANSFORMER (TRANSDUCTOR) BASED ON CONDUCTIVE COMPOSITES

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on May 17, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 5/17/04

U.S. Patent 5,771,027 to Marks et al., "Composite Antenna," describes a composite antenna having a grid comprised of electrical conductors woven into the warp of a resin reinforced cloth forming one layer of a multi-layer laminate structure of an antenna.

U.S. Patent 6,249,261 to Solberg, Jr. et al., "Polymer, Composite, Direction-Finding Antenna," describes a direction-finding material constructed from polymer composite materials, which are electrically conductive.

U.S. Patent 4,748,436 to Kanamori et al., "Noise Prevention High Voltage Resistance Wire," describes a high voltage resistance wire formed of a conductive composite mixed with a polymer.

U.S. Patent 4,035,710 to Joyce, "Pulse Width Modulated Voltage Regulator-Converter/Power Converter Having Means for Improving the Static Stability Characteristics Thereof," describes a voltage regulator-converter/power converter, which uses a transinductor, a multiple winding inductive element.

U.S. Patent 5,654,881 to Albrecht et al., "Extended Range DC-DC Power Converter Circuit," describes a single stage power converter. The converter uses a transinductor, a multiple winding inductive element, having a primary winding providing energy storing inductance.

UK Patent Application GB 2 377 449 A to Michael Patrick Sayers, "Electrically conductive polymer composition," discloses an electrically conductive composition which comprises a polymeric material and a plurality of metal fibres dispersed within the polymeric material.

U.S. Patent Application INT-03-001, Serial No. 10/780,214, filed 02/17/04, entitled "Low Cost Antennas and Electromagnetic (EMF) Absorption in Electronic Circuit Packages or Transceivers Using Conductive Loaded Resin-Based Materials," assigned to the same assignee, describes low cost antennas and electromagnetic absorption structures using conductive loaded resin-based materials.

Sincerely,

Stephen B. Ackerman,
Reg. No. 37761

<p>Form PTO-1449 O P F INFORMATION DISCLOSURE CITATION IN AN APPLICATION MAY 19 2004 (Use several sheets if necessary)</p>				Document Number (Opinion)	Assignment Number		
				INT-03-002	10/782, 364		
				Applicant	Thomas Aisenbrey		
				Filing Date	02/19/04		
U. S. PATENT DOCUMENTS							
EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	ALSO DATE X APPROXIMATE	
	5 7710276/23/98		Marks et al.	343	912	4/28/97	
	6 2492616/19/01		Solberg, Jr. et al.	343	801	3/23/00	
	4 7484365/31/88		Kanamori et al.	338	214	5/21/87	
	5 6548818/5/97		Albrecht et al.	363	25	3/1/96	
	40357107/12/77		Joyce	363	37	10/20/75	
FOREIGN PATENT DOCUMENTS							
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
	GB 2 377449 A	1/15/03	United Kingdom	CO8K 3/08	7/06	YES	NO
OTHER DOCUMENTS (Including Author, Title, Date, Portion or Pages, Etc.)							
<p>- U.S. Patent App. INT-03-001, Serial No. 10/780,214, filed 02/17/04, "Low Cost Antennas and Electro-magnetic (EMF) Absorption in Electronic Circuit Packages or Transceivers Using Conductive Loaded Resin-Based Materials", assigned to the same assignee.</p>							
EXAMINER				DATE CONSIDERED			

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.